

ABSTRACT

5 A retainer ring provided in a substrate holder is disclosed, which enables a polishing
profile of the substrate in its entirety, including an edge portion of the substrate, to be
matched to a desired profile. The retainer ring is used in the substrate holder for pressing
the substrate against the polishing pad supplied with the polishing liquid to polish the
substrate. The retainer ring has a ring shape, and includes a ring body for supporting an
10 outer periphery of the substrate pressed against the polishing pad. The ring body has at
least one ring groove formed in a lower surface to be pressed against the polishing pad and
extending concentrically with the ring body, and a barrier for preventing the polishing liquid
from reaching an interior from an exterior of the ring body.

15 FIG. 4